

**AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph beginning on page 9, line 8, with the following rewritten paragraph:

The cover layer 36a is machined to provide a hole 39a through which an electrode 32 is exposed in a predetermined position of the conductor pattern 22 on the top layer, and so is the cover layer 36b to provide another hole ~~39a~~ 39b through which an electrode 37 is exposed in a predetermined position of the conductor pattern 22 on the bottom layer. In this embodiment, the same resin film as for the resin film 23, which is a thermoplastic film with 25 - 75  $\mu$  m thickness, made of a mixture of 65 - 35 % polyetheretherketone resin and 35 - 65 % polyetherimide resin, is used for the cover layers 36a and 36b.